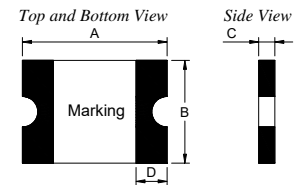


#### 1、Physical Dimensions(size of 1812)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
MSMD030/60	4.37	4.73	3.07	3.41	0.90	1.60	0.30	T035



#### 2、Electrical Characteristics

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> (Max time to trip)		Pd <sub>typ</sub> (W)	R <sub>min</sub> (Ω)	R1 <sub>max</sub> (Ω)
					Current(A)	Time(S)			
MSMD030/60	0.30	0.70	60	10	8.0	0.10	0.8	0.20	2.00

I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25°C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I<sub>max</sub>: Maximum fault current device can withstand without damage at rated voltage.

T<sub>trip</sub>: Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>: Rated working power.

R<sub>min</sub>: Minimum resistance of device prior to trip at 25°C.

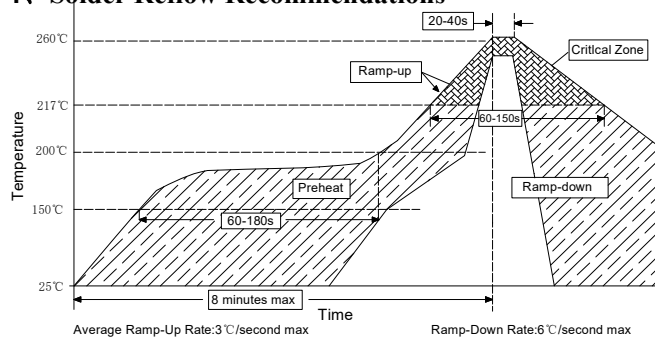
R1<sub>max</sub>: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

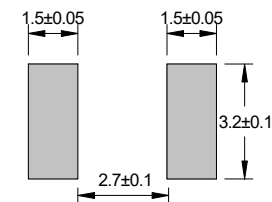
#### 3、Thermal Derating

MSMD030/60	Maximum ambient operating temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
Hold Current(A)	0.44	0.40	0.36	0.30	0.28	0.26	0.24	0.20	0.16
Trip Current(A)	1.03	0.93	0.84	0.70	0.65	0.61	0.56	0.47	0.37

#### 4、Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

#### 5、Package Information

Packing quantity: 1500PCS/Reel

Note: Reel packaging per EIA-481-1 standard